



Material Content Data Sheet



Sales Product Name				BSC014N06NS		Issued		25. September 2017	
MA#				MA001003250					
Package				PG-TDSON-8-17		Weight*		119.51 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.818	1.52	1.52	15216	15216	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		316		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	copper	7440-50-8	37.762	31.61	31.65	315971	316382	
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	372	372	
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		711		
	plastics	epoxy resin	-	6.033	5.05		50484		
	inorganic material	silicondioxide	60676-86-0	36.370	30.43	35.55	304328	355523	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12147	12147	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1385	1385	
solder	noble metal	silver	7440-22-4	0.062	0.05		521		
	non noble metal	tin	7440-31-5	0.050	0.04		417		
	non noble metal	lead	7439-92-1	2.380	1.99	2.08	19912	20850	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	zinc	7440-66-6	0.013	0.01		112		
	non noble metal	iron	7439-89-6	0.269	0.22		2248		
	non noble metal	copper	7440-50-8	10.909	9.13	9.36	91281	93669	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	zinc	7440-66-6	0.026	0.02		221		
	non noble metal	iron	7439-89-6	0.529	0.44		4427		
	non noble metal	copper	7440-50-8	21.482	17.98	18.45	179753	184456	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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